

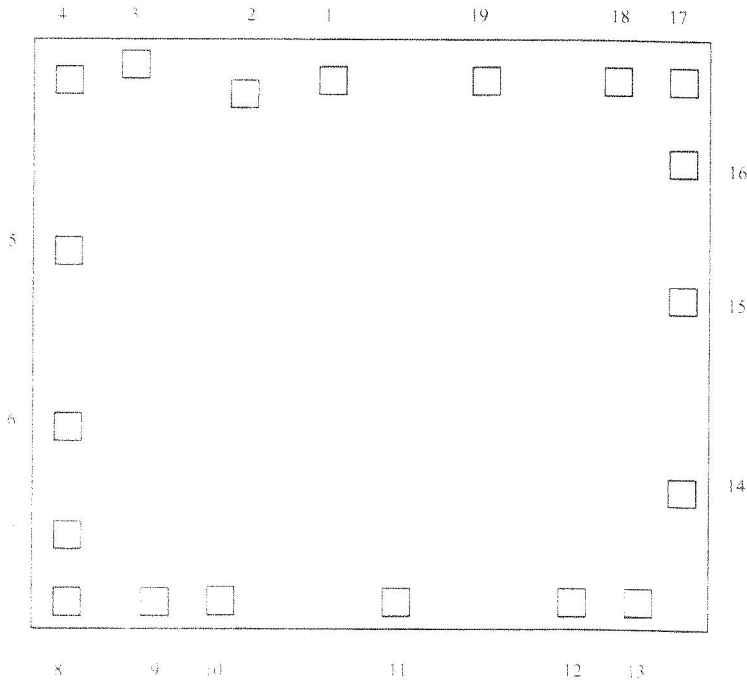


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PAD FUNCTIONS



- 1 -VIN
- 2 V Ref (2.5V)
- 3 GROUND
- 4 GROUND
- 5 WINDOW ADJUST
- 6 SENSE 4 INVERT INPUT
- 7 SENSE 4
- 8 SENSE 3
- 9 SENSE 2
- 10 SENSE 1
- 11 OV DELAY
- 12 OV FAULT
- 13 UV FAULT
- 14 UV DELAY
- 15 POWER OK
- 16 LINE / SWITCHER SENSE
- 17 G.P.OP-AMP OUT
- 18 G.P.OP-AMP N.INV
- 19 G.P.OP-AMP INV

The information given is believed to be correct at the time of issue.

Please verify your requirements prior to commencement of any assembly process, as no liability for omission or error can be accepted.

Chip back potential is the level at which bulk silicon is maintained either by bond pad connection or in some cases the potential to which the chip back must be connected if stated above.

Note: 1 mil = 0.001inch

APPROVED	UC1903	DIE INFORMATION
GB		DIMENSIONS (Mils): 122 x 109 x 9
DATE: 28/06/2006	TEXAS INSTRUMENTS	BOND PADS (Mils): 4 x 4
SERIAL NUMBER		MASK REF: BA
008501		GEOMETRY:
		BACK CONNECTION: FLOATING
		METALLISATION
		TOP: Al
		BACK: Si